

SDM4407AQ

-30V P-Channel MOSFETs

Rev A.0

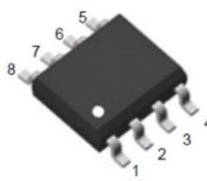
Feature

- ✧ Excellent $R_{DS(ON)}$
- ✧ Low Gate Charge
- ✧ High current Capability
- ✧ Green product (RoHS compliant), lead free
- ✧ 100% UIS Tested

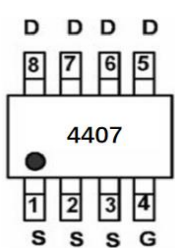
Product Summary

V_{DS}	-30	V
$V_{GS(th_Typ)}$	-1.7	V
$R_{DS(ON)_Typ}$ (at $V_{GS} = -10V$)	9.3	m Ω
I_D	-12	A

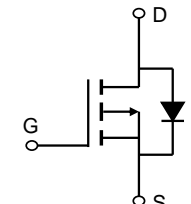
Type	Package	Marking	Outline	Media	Quantity (pcs)
SDM4407AQ	SOP-8	4407	Tape	13" Reel	4000



SOP-8 Top View



Marking and Pin Assignment



Schematic Diagram

Absolute Maximum Ratings (Rating at $T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Maximum	Unit
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	I_D	$T_A=25^\circ C$	-12
		$T_A=100^\circ C$	-7.6
Pulsed Drain Current ⁽¹⁾	I_{DM}	-48	A
Maximum Body-Diode Continuous Current	I_S	-12	A
Avalanche Energy ⁽²⁾	E_{AS}	64	mJ
Power Dissipation	P_D	1.5	W
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ C$

Electrical Characteristics (Rating at $T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=-250\mu\text{A}$, $V_{GS}=0\text{V}$	-30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-30\text{V}$, $V_{GS}=0\text{V}$	-	-	-1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{DS}=0\text{V}$, $V_{GS}=\pm 20\text{V}$	-	-	± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=-250\mu\text{A}$	-1.0	-1.7	-2.5	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance ⁽⁴⁾	$V_{GS}=-10\text{V}$, $I_D=-12\text{A}$	-	9.3	14	m Ω
		$V_{GS}=-4.5\text{V}$, $I_D=-8\text{A}$	-	14	20	
V_{SD}	Diode Forward Voltage	$I_S=-30\text{A}$, $V_{GS}=0\text{V}$	-	-	-1.2	V
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}$, $V_{DS}=-15\text{V}$, $f=1\text{MHz}$	-	2251	-	pF
C_{oss}	Output Capacitance		-	305	-	pF
C_{rss}	Reverse Transfer Capacitance		-	221	-	pF
SWITCHING PARAMETERS						
Q_g	Total Gate Charge	$V_{GS}=-10$ to 0V , $V_{DD}=-15\text{V}$ $I_D=-10\text{A}$	-	39	-	nC
Q_{gs}	Gate Source Charge		-	6.9	-	nC
Q_{gd}	Gate Drain Charge		-	9	-	nC
$t_{D(on)}$	Turn-On Delay Time	$V_{GS}=-10\text{V}$, $V_{DS}=-15\text{V}$, $I_D=-10\text{A}$, $R_{GEN}=3\Omega$	-	5.9	-	ns
t_r	Turn-On Rise Time		-	1.9	-	ns
$t_{D(off)}$	Turn-Off Delay Time		-	89	-	ns
t_f	Turn-Off Fall Time		-	51	-	ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=-10\text{A}$, $di/dt=100\text{A}/\mu\text{s}$	-	13	-	ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=-10\text{A}$, $di/dt=100\text{A}/\mu\text{s}$	-	5.9	-	nC

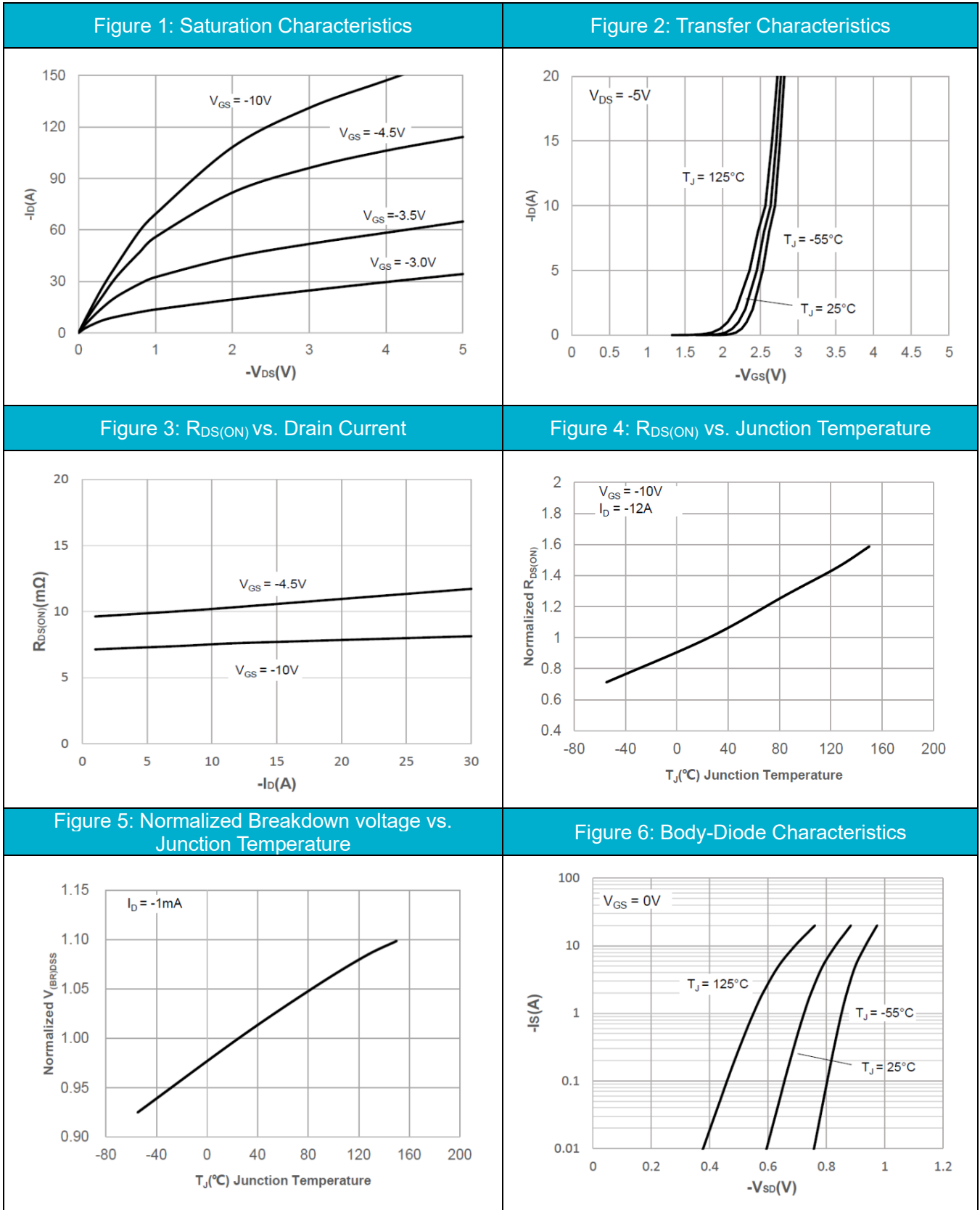
Thermal Resistances

Symbol	Parameter	Typ	Max	Unit
$R_{\theta JA}$	Thermal resistance from junction to ambient ⁽³⁾	-	82	°C /W

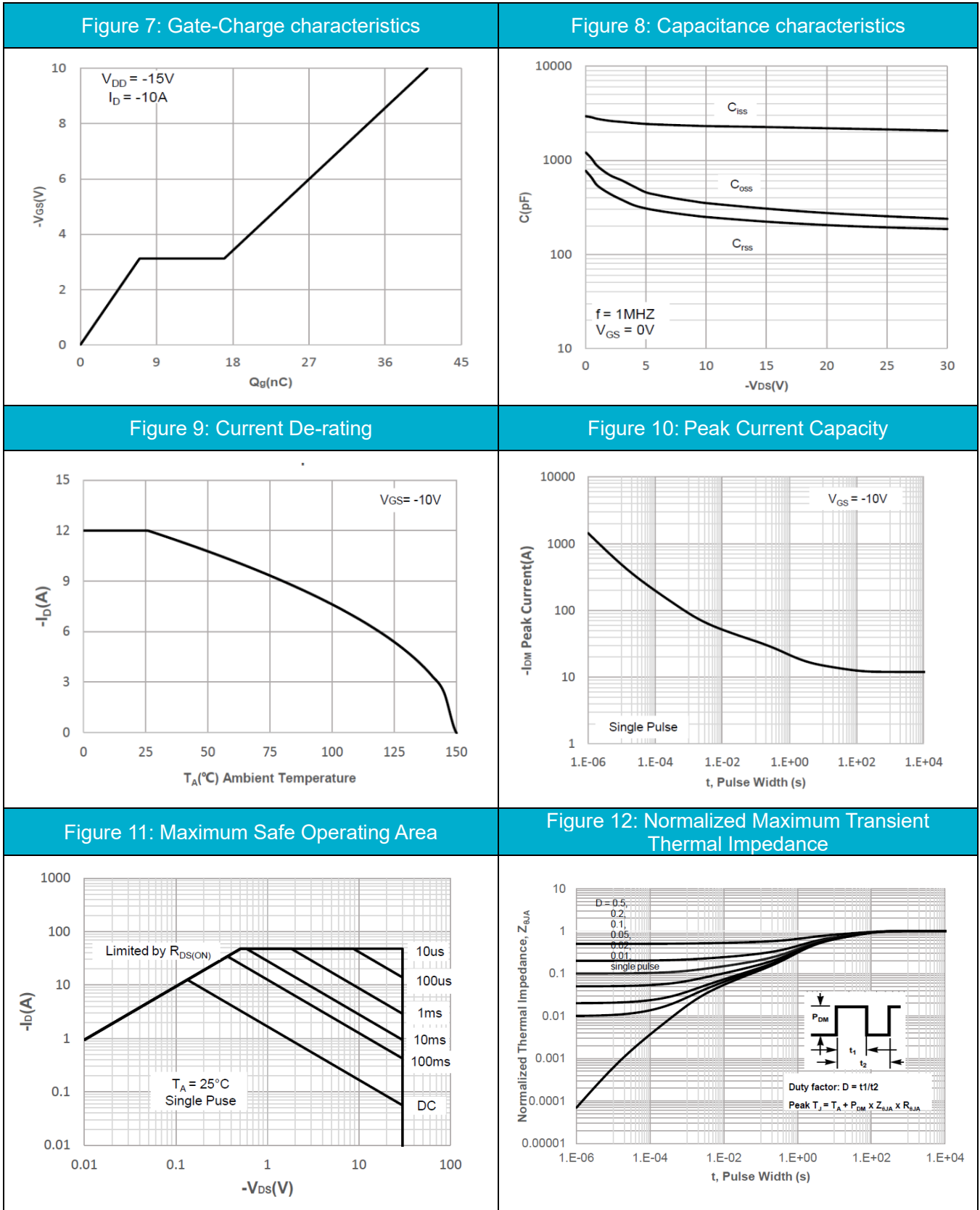
Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
2. EAS condition: Starting $T_J=25C$, $V_{DD}=-15V$, $V_G=-10V$, $R_G=25ohm$, $L=0.5mH$, $I_{AS}=-16A$
3. $R_{\theta JA}$ is measured with the device mounted on a $1inch^2$ pad of 2oz copper FR4 PCB
4. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 0.5\%$.

Typical Electrical and Thermal Characteristics



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Test Circuit

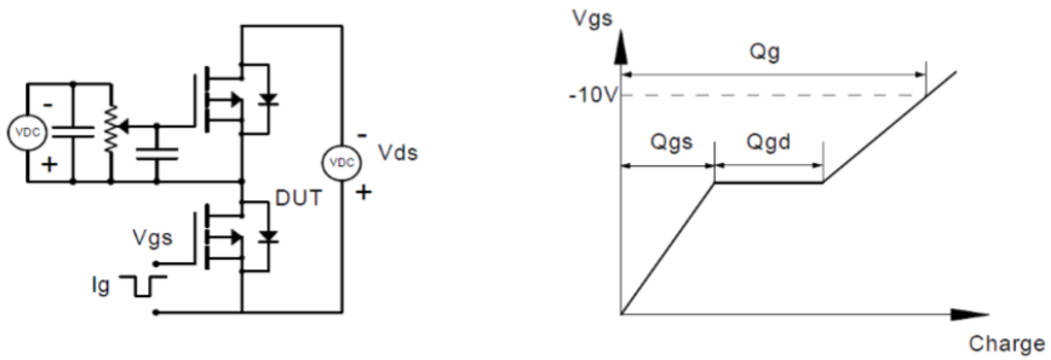


Figure1: Gate Charge Test Circuit & Waveforms

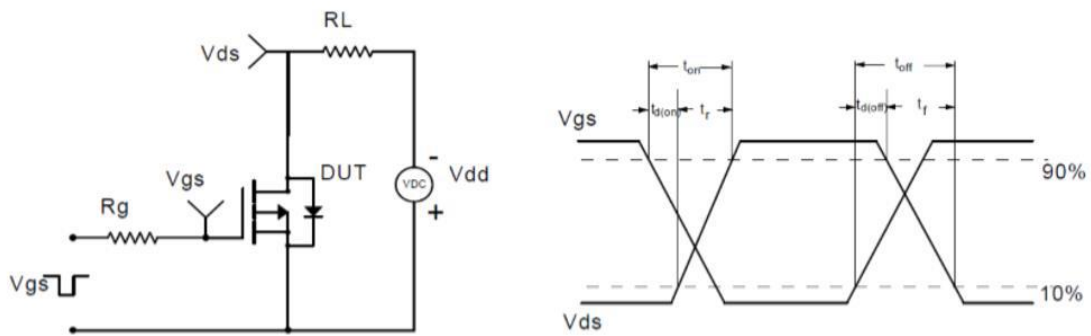


Figure2: Resistive Switching Test Circuit & Waveforms

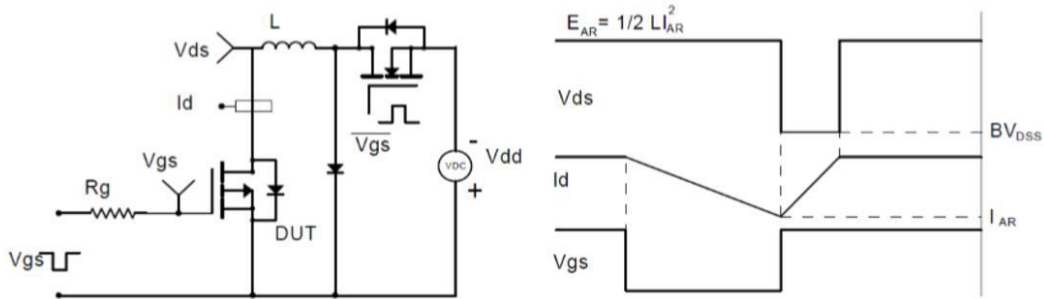


Figure3: Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

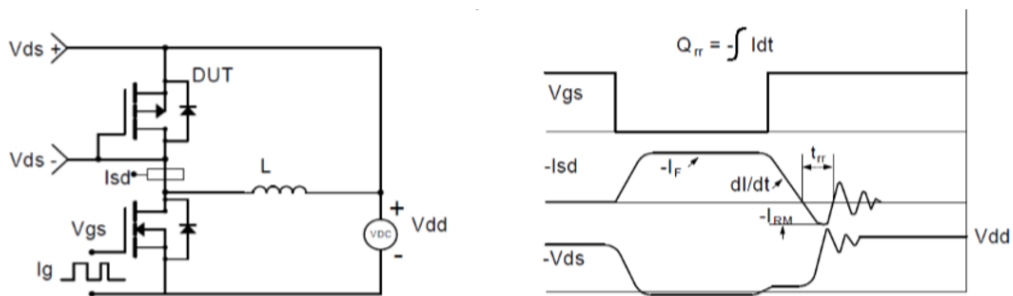
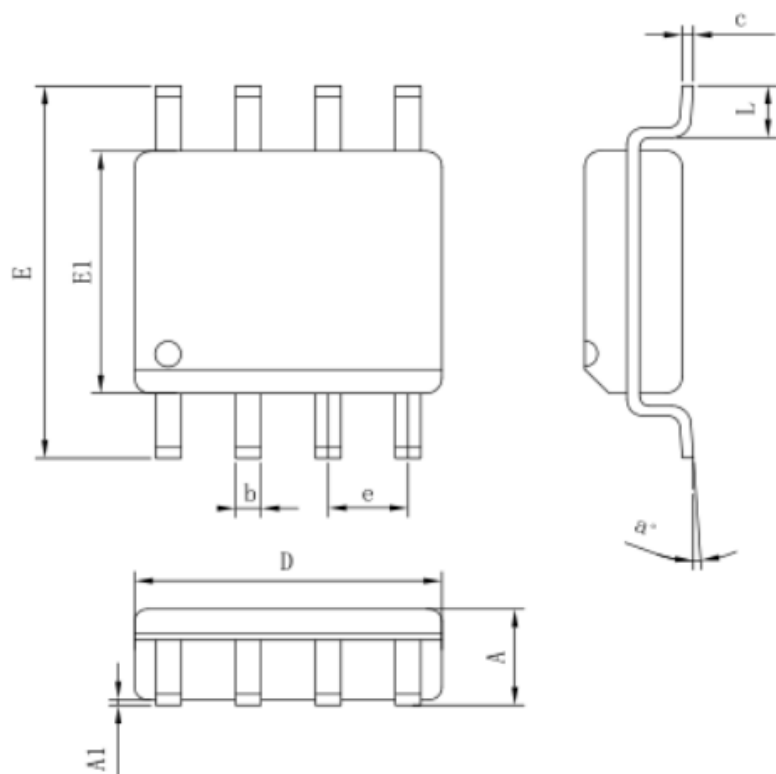


Figure4: Diode Recovery Test Circuit & Waveforms

SOP-8 Package Information



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	--	--	1.75
A1	0.10	--	0.23
b	0.35	--	0.48
c	0.19	--	0.25
D	4.70	4.90	5.00
E	5.80	6.00	6.20
E1	3.70	3.90	4.10
e	1.27BSC		
L	0.50	--	0.80
a°	0°	--	8°